



Rev. A May.-2020

SOD-323



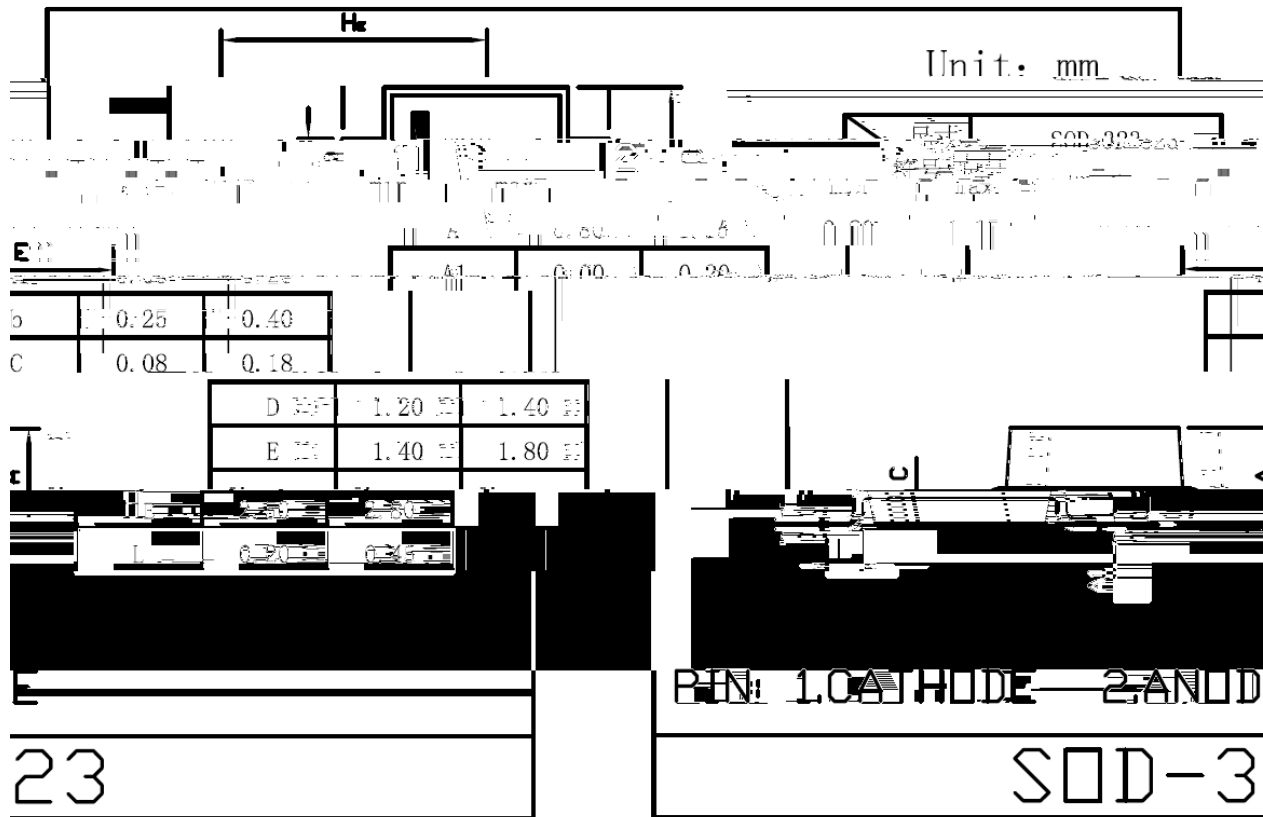
Parameter	Symbol	Rating	Unit
Maximum recurrent peak reverse voltage	V_{RM}	45	V
DC reverse voltage	V_R	40	V

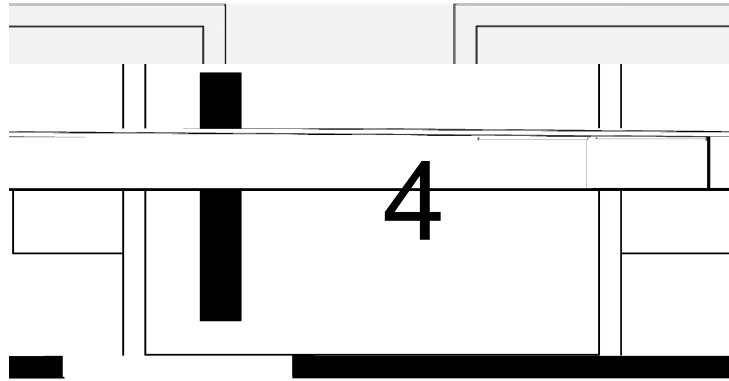
Continuous forward current





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4

Note:

4 : Product Type.



Temperature Profile for IR Reflow Soldering (Pb-Free)



说明：

- 1、预热温度 150~180°C，时间 60~90sec;
- 2、峰值温度 245±5°C，时间持续为 5±0.5sec;
- 3、焊接制程冷却速度为 2~10°C/sec.

Note:

- 1.Preheating:150~180°C, Time:60~90sec.
- 2.Peak Temp.:245±5°C, Duration:5±0.5sec.
3. Cooling Speed: 2~10°C/sec.

Temperature Profile for IR Reflow Soldering (Pb-Free)

温度：260±5°C

时间：10±1 sec.

Temp.:260±5°C

Time:10±1 sec

Temperature Profile for IR Reflow Soldering (Pb-Free)

卷盘包装 / REEL

Package Type	Units			Units/Outer Box 只/箱	Dimension (unit: mm)		
	只/卷盘	卷盘/盒	只/盒		Reel	Inner Box fl	Outer Box L